

# Stroke Rehabilitation Hand Device (Checkpoint)

---

TEAM #15

MEMBERS: JAKE CARDUCCI, KEVIN OLDS (MENTOR)



# Planned Goal

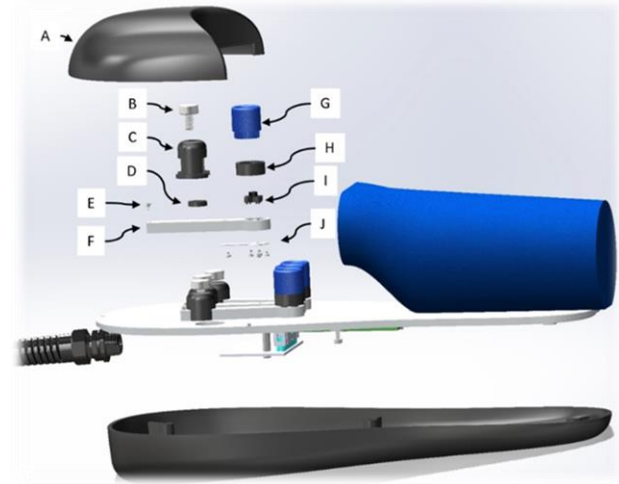
---

To get clinical engineering approval and an IRB-approved clinical study for a hand rehabilitation device, to design and fabricate an improved version of the device based on study feedback, and to get preliminary study feedback for the revised version.



# Technical Summary (Current Prototype)

- Hand fits in adjustable brace, secures to base
- Finger fits in silicon cup(s), force detected at base
- Force signals sent to computer and processed into usable information

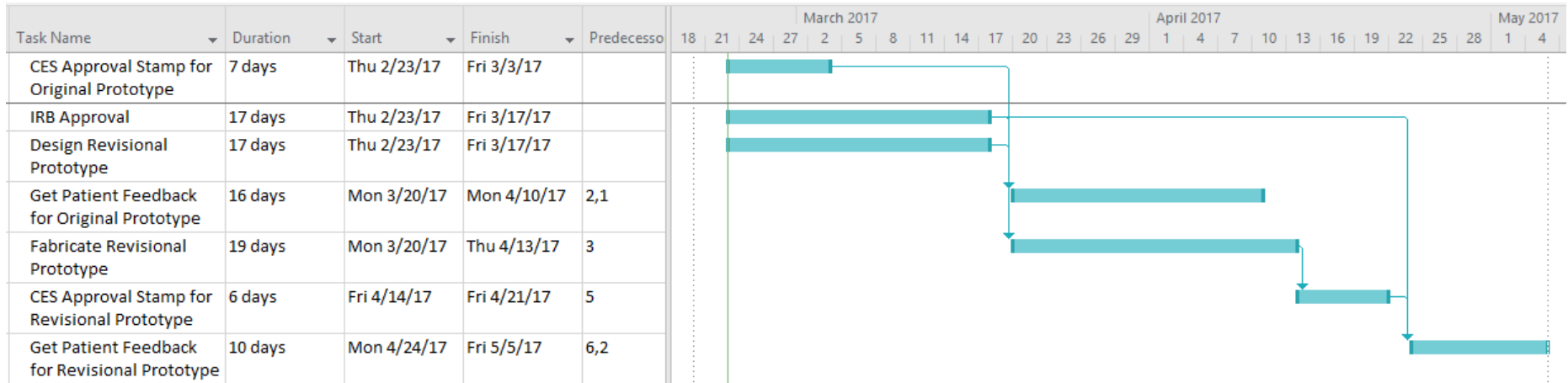


# Technical Approach (Planned Prototype)

- Increase digit count from two to five
  - 8 → 20 signal channels
- Modify mechanisms for easier component attachment and removal (brace, retention cups, etc.)
- Properly calibrate force sensors with high sensitivity
- Modified adjustable force beam designs for each finger



# Original Schedule



# IRB / CES Update

- Compliance Training
  - Human subjects research (CITI)
  - HIPAA for research
- Clinical engineering and research
  - Wrote select...
  - Ex: 3...

No first prototype testing

myLearning

THE JOHNS HOPKINS  
UNIVERSITY  
MEDICINE

The logo for the CITI PROGRAM, featuring a stylized globe icon to the left of the text "CITI PROGRAM".

The logo for the Laboratory for Computational Sensing + Robotics, featuring a stylized human figure with a yellow circle above its head.  
LABORATORY FOR  
**Computational  
Sensing + Robotics**  
THE JOHNS HOPKINS UNIVERSITY



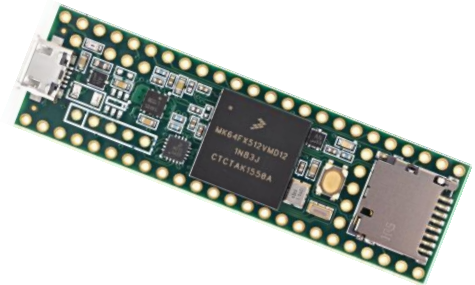
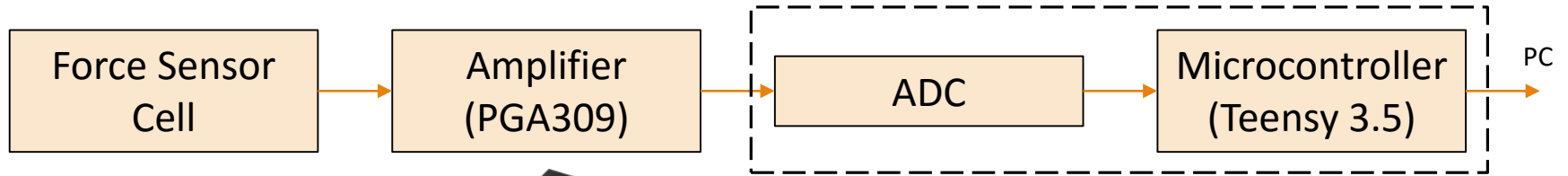
# IRB / CES Update

---

- Western University collaboration
  - Device validation study
  - Funded through CA grant
  - Targeted at clinics across Canada
  - 3-4 devices ready by mid-May
- **Therefore, planned / completed tasks related to IRB and CES approval are on hold until further notice**

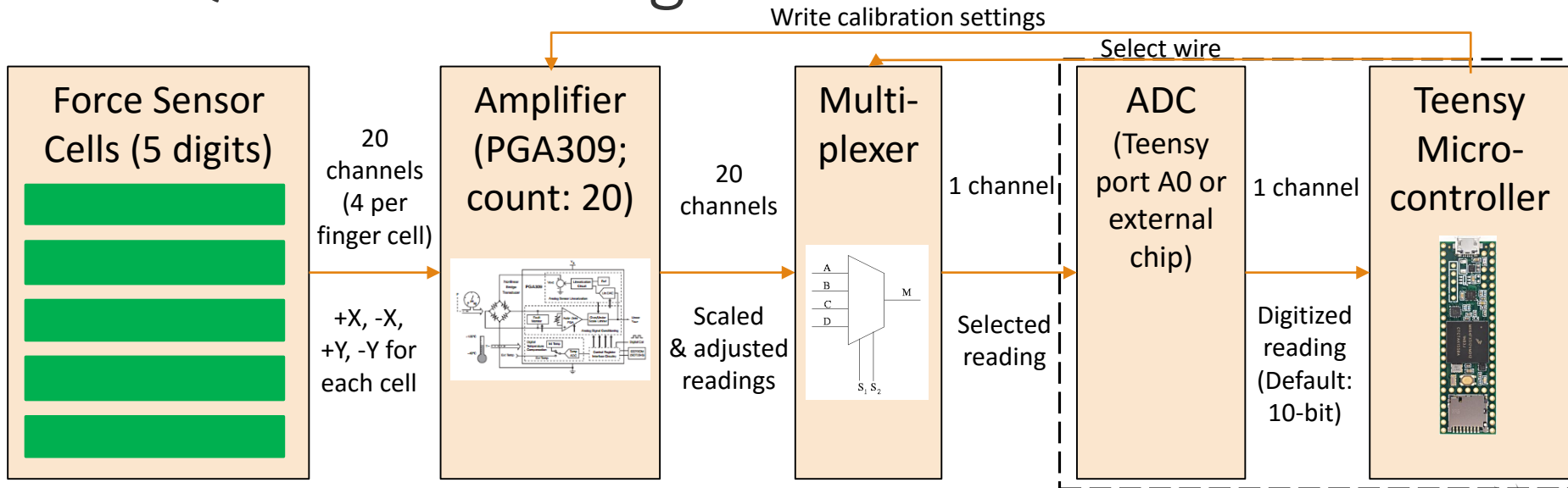


# DAQ Channel Design





# DAQ Channel Design



+Z, -Z can be found from +X, -X, +Y, -Y

# DAQ Channel Design

- PGA309 Amplifier
  - Programmable gain controller
  - 0.25 in x 0.20 in x 0.05 in\*
  - Potential gain range: 2.7V/V to 1152 V/V
  - Digital calibration over I<sup>2</sup>C communication
  - Internal fault detection
  - Temperature-based offset adjustment



- Teensy 3.5 USB Microcontroller
  - 32-bit width, 120 MHz clock, 192 KB RAM
  - Very small footprint (2.4 by 0.7 inches)\*
  - Programmable via Arduino IDE
  - 2 to 12 MHz built-in ADC sampling rate (all bit resolutions)



\*(By comparison, NI DAQ board: 3.9 in x 2.5in x 12 mm)

# DAQ Channel Design

- 3-stage gain amplifier
- Front-End PGA (GI = 4 to 128)
- Fine DAC (GD = 0.33 to 1)
- Output Amp (GO = 2 to 9)
- Transfer Function
- $V_{out} = [(sign_{mux} * V_{in,diff} + V_{offset,coarse}) * GI + V_{zero,DAC}] * GD * GO$
- Except for input voltage and multiplex sign, you can program each one of these!

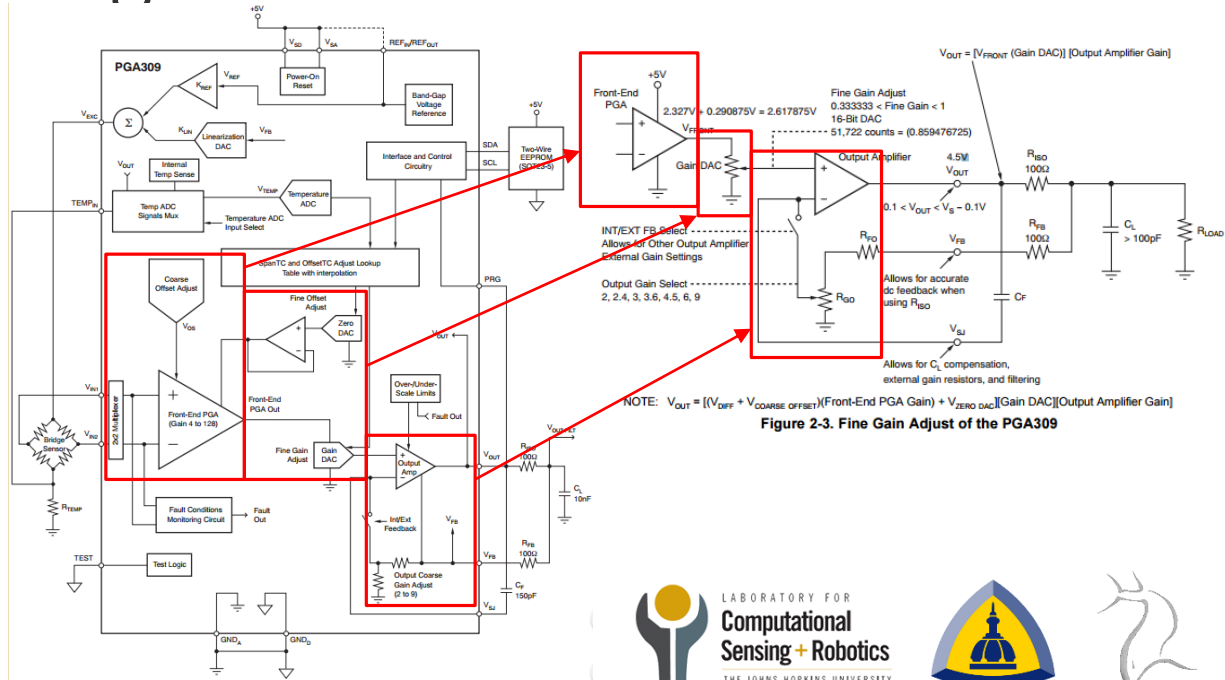
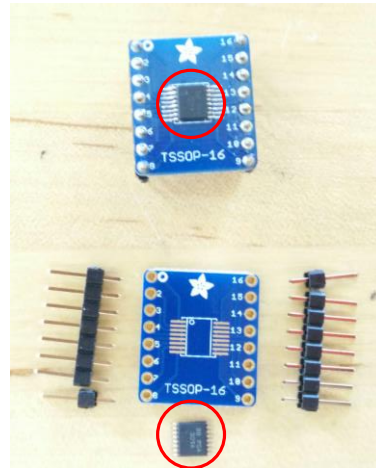


Figure 24. Simplified Diagram of the PGA309 in a Typical Configuration

Figure 2-3. Fine Gain Adjust of the PGA309

# DAQ Channel Design

- Amplifier verification testing
  - Needed early in design
- Soldering
  - TSSOP-16 breakout adapter (0.65 mm pin separation)
  - Breadboard headers (2.54 mm pin separation)
  - Former required more care and caution than the latter



# DAQ Channel Design

- Q: How to know if amplification on the PGA309 is working?
- A: Use the test pin configuration.
- How?: Bring test port (pin 9) to HIGH
- Result:  $V_{out}$  enabled & default gain/offset values used

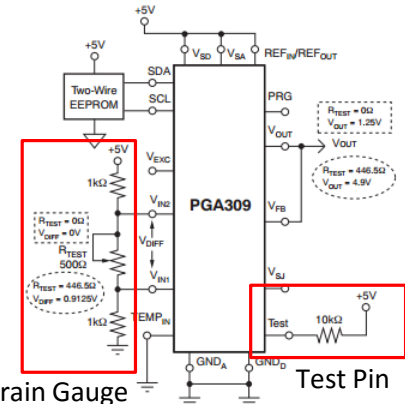
Table 3-8. POR States for Key Parameters

Parameter	POR State
Coarse Offset	0V
Front-End PGA Gain	4 ( $V_{IN1} = V_{INP}$ , $V_{IN2} = V_{INN}$ )
Gain DAC	0.5
Output Amplifier Gain	2
Zero DAC	0.25 $V_{REF}$
$V_{REF}$ Select	External Reference
Lin DAC	0
Fault Monitor	Disabled
Over/Under-Scale	Disabled
$V_{EXC}$	Disabled
$I_{TEMP}$	Disabled
Temp ADC	External Signal Mode

$$V_{out} = [(sign_{mux} * V_{in,diff} + V_{offset,coarse}) * GI + V_{zero,DAC}] * GD * GO$$

$$V_{out} = [(sign_{mux} * V_{in,diff} + 0) * 4 + 0.25 * V_{ref}] * 0.5 * 2$$

$$V_{out} = abs(V_{in,diff}) * 4 + 0.25 * V_{ref}$$






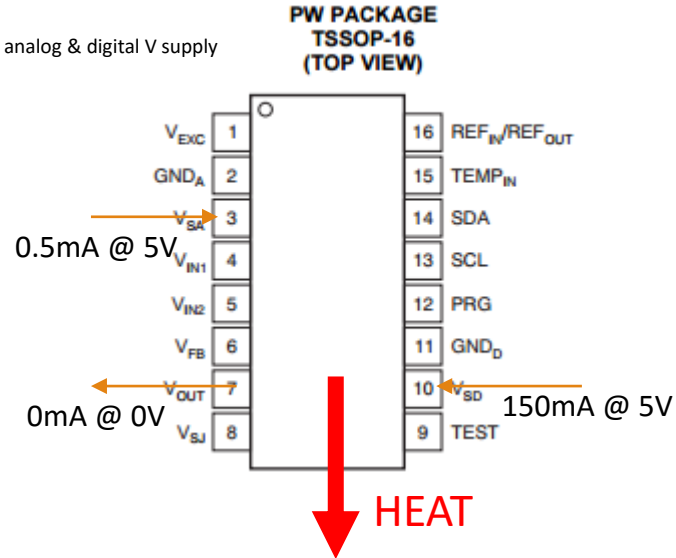
NOTE: Two conditions for  $V_{DIFF}$  and the resulting  $V_{OUT}$  are shown in this figure. Condition one is in a dashed, square box. Condition two is shown in a dashed oval.

Figure 3-5. Signal Path Functional Check with Test = '1' on Power-Up

# DAQ Channel Design

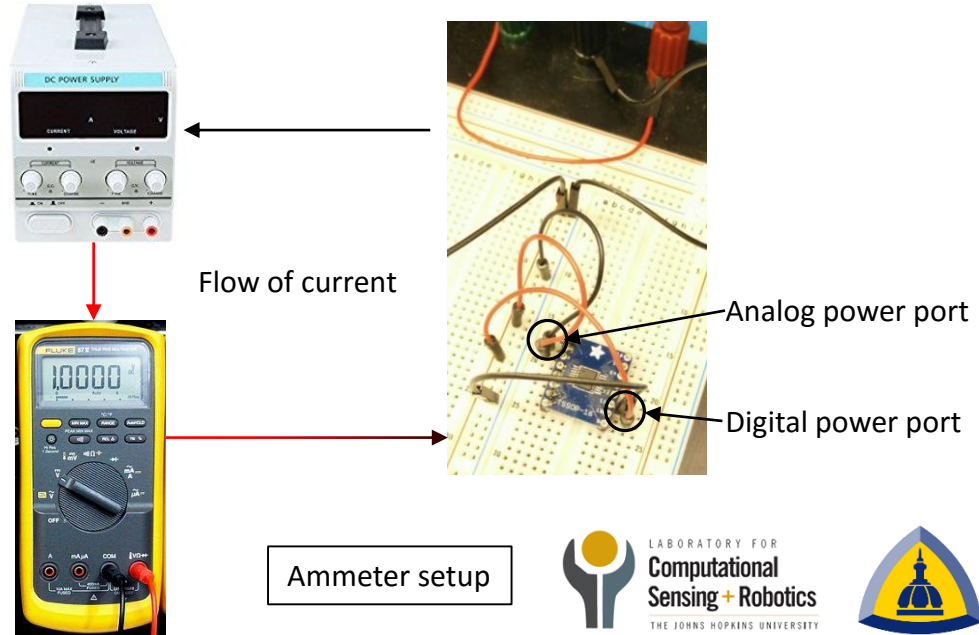
- Connected PGA power to Teensy USB power
- Result?
  - Chip temp increased rapidly!
  - $I_{\text{analog}} \approx 0.5 \text{ mA}$  into pin 3
  - $I_{\text{digital}} \approx 150 \text{ mA}$  into pin 10
  - Neither pin should exceed 10 mA
  - Something went wrong!

Ground (0 V)     $V_{\text{cc}}$  for analog & digital V supply (+5 V)



# DAQ Channel Design

- Solution process
  - Isolate power connections; disconnect other connections
  - Use controlled DC lab power supply direct to PGA309
  - Chip only heated from connection hot-swaps
    - Difference in supply voltages  $> 200$  mV
- Final solution
  - Avoid hot-swaps
- Result?
  - Chip never heats from DC supply or standalone charger



# Lesson #1

---

*Never rush your debugging and validation processes.*

*Be mindful of what and when you connect and disconnect components.*

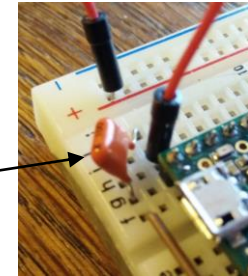
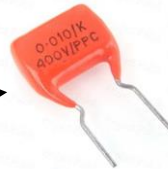
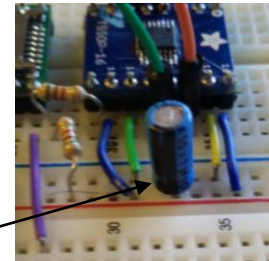
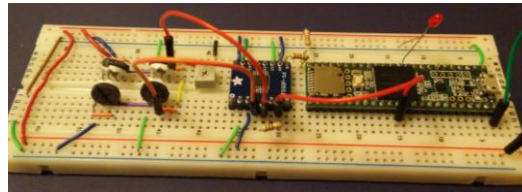
(i.e. don't hotswap your power connections when two of them should be nearly the same at all times; turn off total power at the source if you need to modify connections)





# DAQ Channel Design

- Problem: chip still heated unpredictably from USB power
- Theory: Inconsistent supply from USB, leading to exceeding 200 mV supply diff
- Possible solution: add decoupling capacitors between power & ground rails
  - 1  $\mu\text{F}$  near chip: charge reservoir to smooth voltage
  - 0.01  $\mu\text{F}$  near power source: reduce noise from supply
- Result?:
  - Chip has not overheated since



# Lesson #2

---

*It is rarely a bad idea to use decoupling capacitors in electronics design, even for circuits with DC power.*

*So use them whenever possible.*

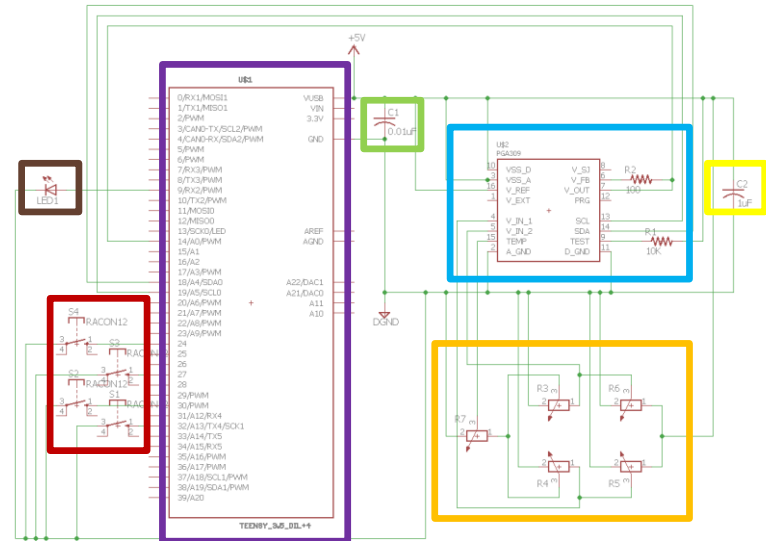
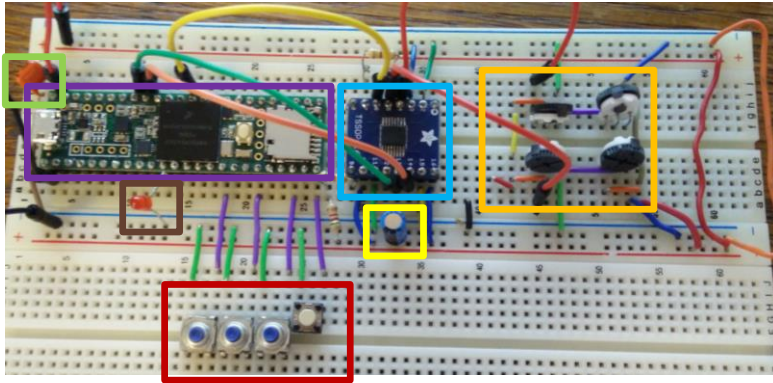
## Lesson #2.5

*Debugging electronic designs can be particularly frustrating, much like finding a needle in a prairie field.*



# DAQ Channel Design

Final calibration setup



# DAQ Channel Design

---

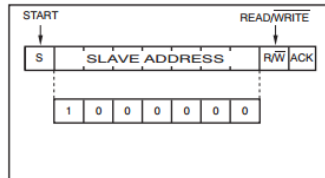
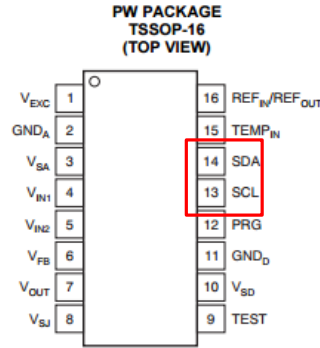
$V_{in,1}$	$V_{in,2}$	$V_{out,meas}$	$V_{out,calc}$	Error
2.140	1.653	3.257	3.245	0.370%
1.355	0.682	4.000	3.989	0.276%
0.989	0.435	3.515	3.513	0.057%

Test Configuration Readings ( $V_{ref} = 5.186 \text{ V}$ )

$V_{out,calc}$  found from Power-on Reset TF

# DAQ Channel Design

- Q: How do we modify gain and offset parameters?
- A: I<sup>2</sup>C
  - Two-wire communication protocol
  - Data on SDA line (pin 14)
  - Clock on SCL line (pin 13)
- PGA309 designed for EEPROM chips
  - Why not just use the Teensy as a master?
  - Make PGA a slave device



PGA309 Control Byte Allocation

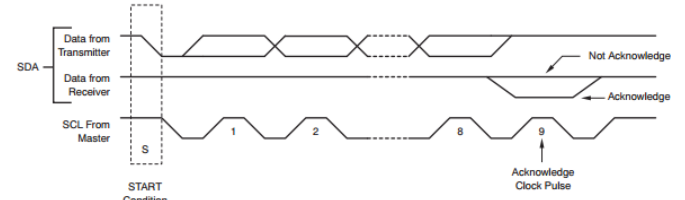
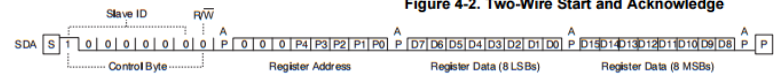
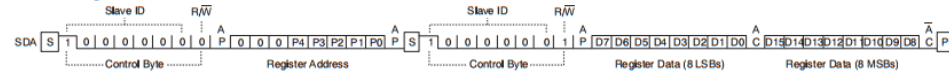


Figure 4-2. Two-Wire Start and Acknowledge

Writing Timing: Two-Wire



Read Timing: Two-Wire

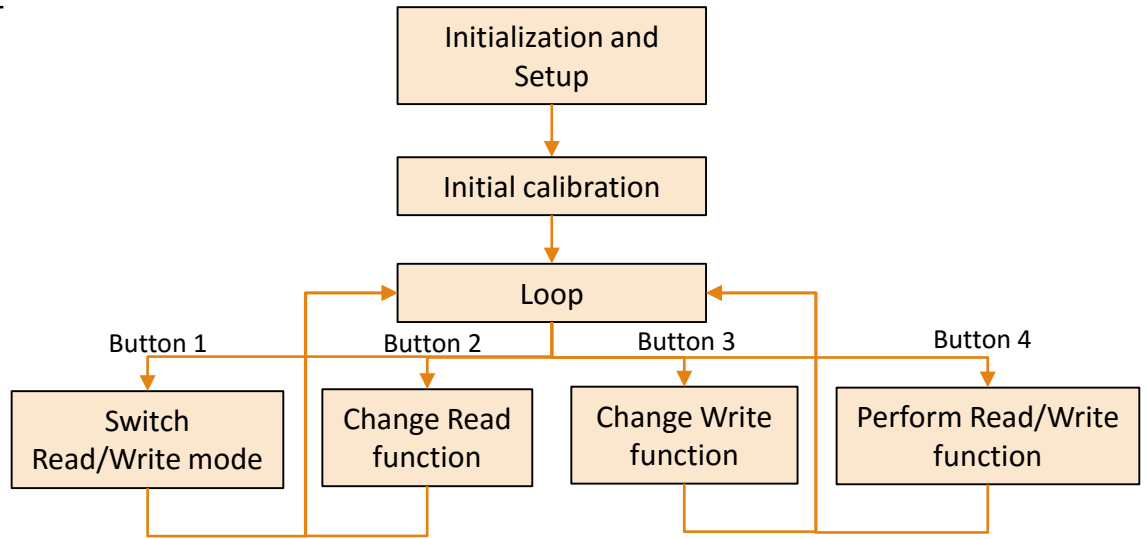


- NOTES: S = START Condition of Two-Wire Protocol  
 P = STOP Condition of Two-Wire Protocol  
 A = Acknowledge from Controller  
 C = Acknowledge from PGA309  
 $\bar{A}$  = Not Acknowledge from Controller  
 $\bar{C}$  = Not Acknowledge from PGA309

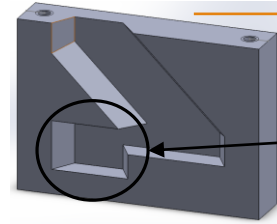
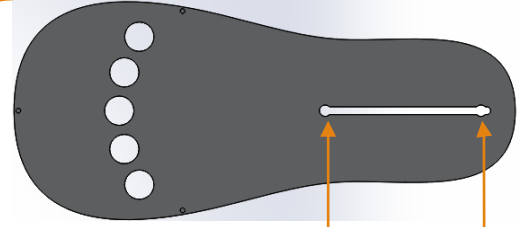
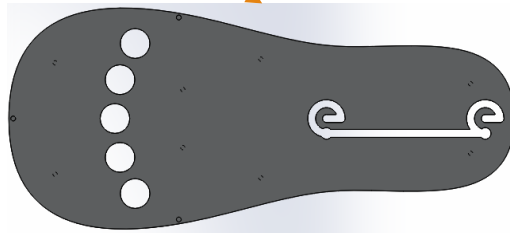
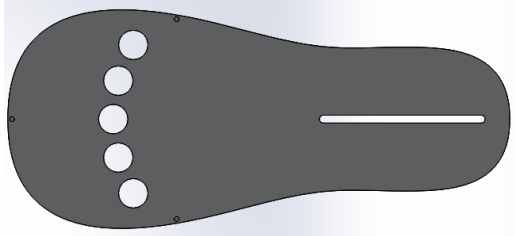
Figure 4-4. Two-Wire Access to PGA309 Timing

# DAQ Channel Design

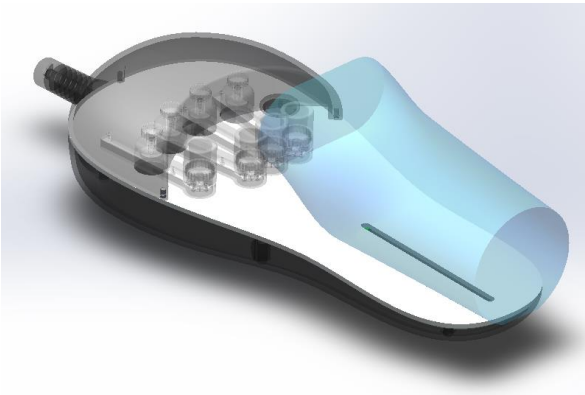
- Current progress & plan
  - PGA309-to-Teensy I<sup>2</sup>C Arduino library
    - General flow of functions on right
    - Code available on project site
  - ADC selection
    - High sampling rate desired
    - Teensy can provide at least 102.8 kHz / channel
    - External hardware packages
  - Filter design
    - Passive low-pass
    - Reduce noise while amplifying signal → increase SNR
  - Fabricate PCB in Eagle



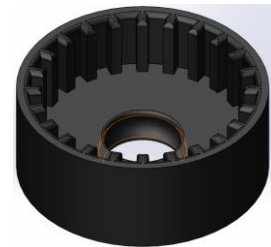
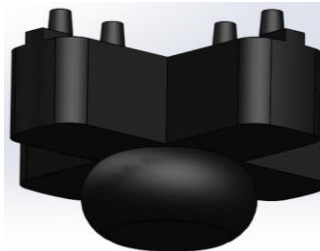
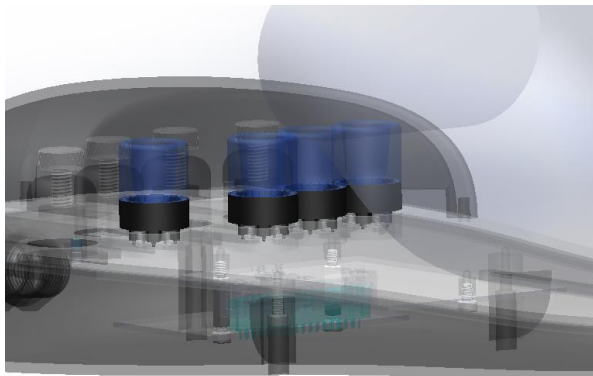
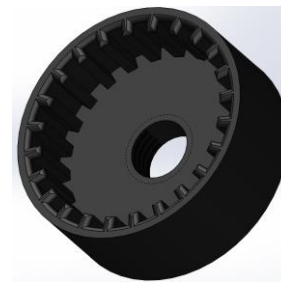
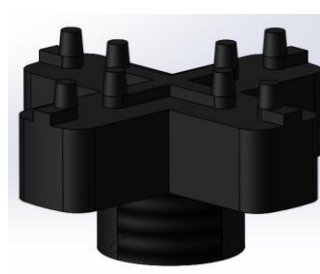
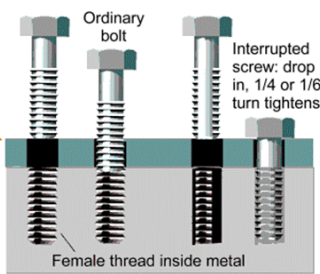
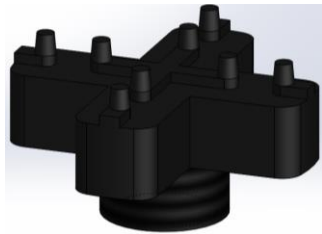
# Arm Brace Attachment Design



Mirrored pair underneath catches fastener nuts here



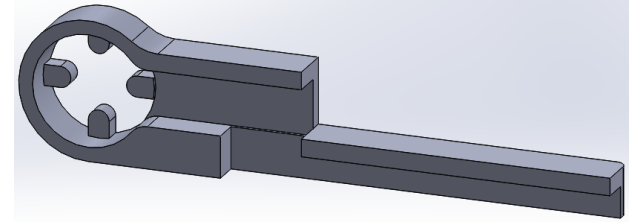
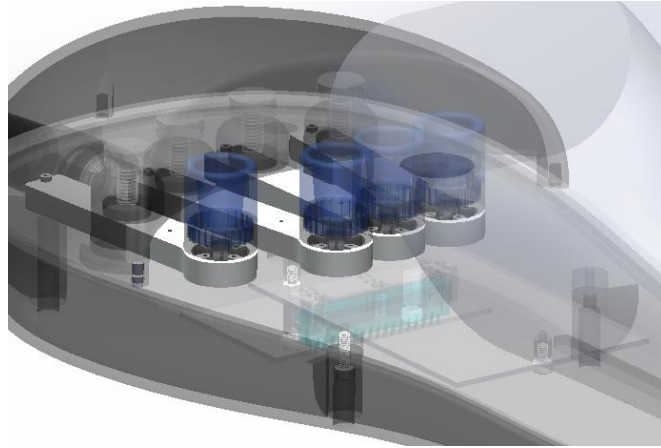
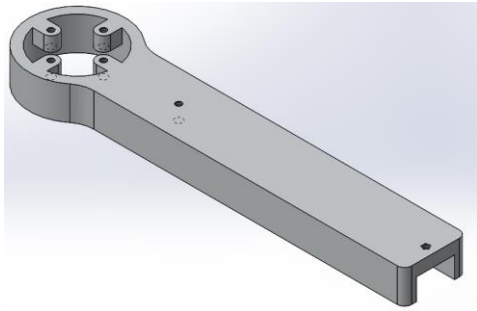
# Base Cap Attachment Design



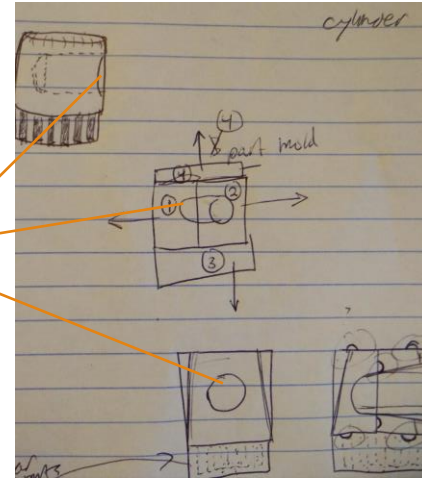
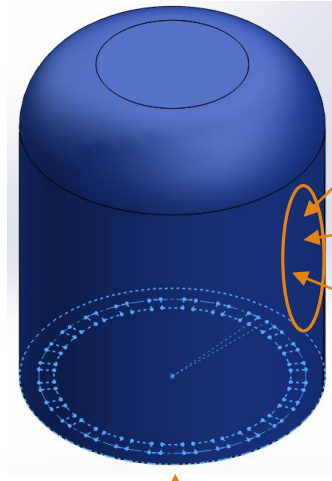
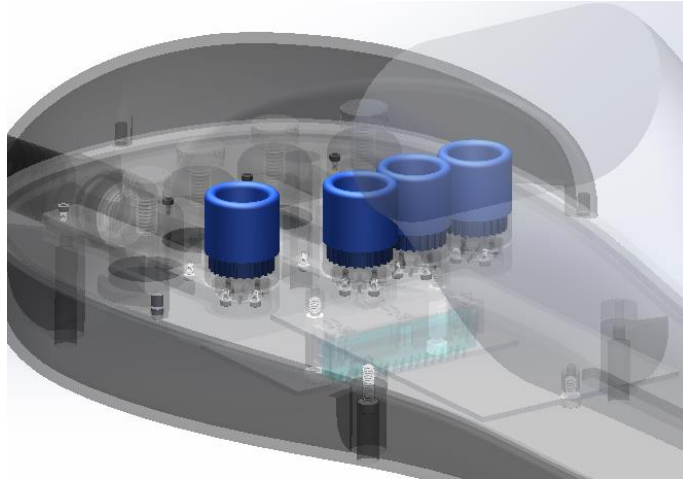
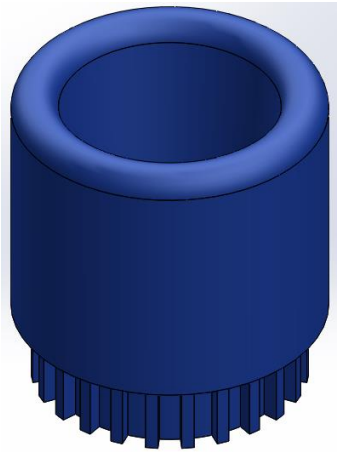


# Thumb Retention Cap Design

---



# Thumb Retention Cap Design



# Lesson #3

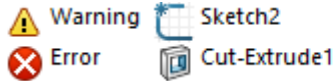
---

*Make sure you clear out any ambiguities when defining project specifications or requirements as early as you can.*

(i.e. a violation of an assumption regarding a project specification may lead to wasted creative energy, time, and resources typically)

## Lesson #3.5 or #4

*Be careful when reverse-engineering SolidWorks part models with constraint geometry established, lest you induce its wrath.*

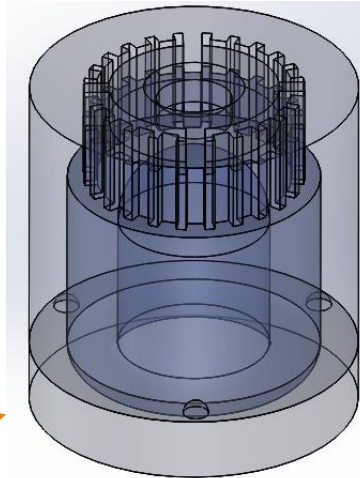


Could not find face or plane.  
Operation failed due to geometric condition.



# Part Fabrication and Modeling

- Current progress & plan
  - Finish CAD model for thumb retention cap
  - Evaluate alternative designs
- Fabrication
  - Aluminum machining
  - Nylon 3D printing
    - Use ProtoLabs service (1-day)
    - In-house machine shop
  - Silicone mold
    - In-house vacuum chamber
    - Plentiful silicone on hand



proto labs®

# Current Goal

---

To design a hand rehabilitation device based on technical goals and client needs, to fabricate two models of the revised design, and to get preliminary study feedback for the revised version (if possible).



# Tasks and Deliverables

Minimum Tasks	Planned Date	Expected Date	Associated Deliverable
Send the existing prototype to clinical engineering team at JH Hospital; get approval stamp	03/03/2017	N/a	Correspondence and approval documents
Get IRB approval for a clinical study	03/17/2017	N/a	Correspondence and approval documents
Design a revised prototype on paper and in CAD <ul style="list-style-type: none"> <li>• Easily removable arm brace</li> <li>• Appropriate design for thumb force sensor</li> <li>• Snap-on mechanism for finger retention cup adapter</li> <li>• PCBs for microcontroller and signal processing to support 5 fingers</li> </ul>	03/17/2017	04/03/2017	Schematics and diagrams associated with each subsystem
Get feedback from at least 5 individuals affected by stroke of various degrees	04/07/2017	N/a	Force test results

# Tasks and Deliverables

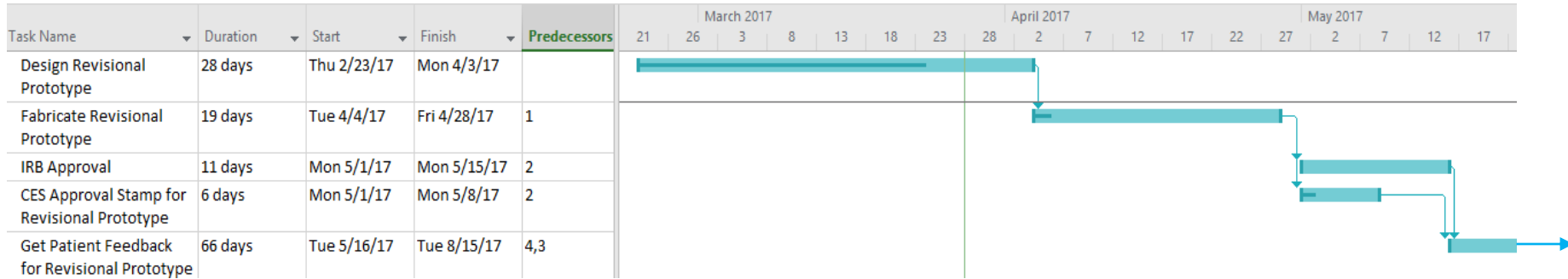
Expected Deliverables and Tasks	Planned Date	Expected Date	Associated Deliverable
Fabricate two devices from revised prototype to implement features developed from <del>patient feedback and other considerations</del> technical objectives and client needs <ul style="list-style-type: none"> <li>All designed components from revision design</li> <li>Breadboard testing of components / soldering PCB parts</li> </ul>	04/14/2017	04/28/2017	Assembled and functional revised prototypes
Maximum Deliverables and Tasks			
Send one revised prototype to clinical engineering, get approval stamp	04/21/2017	05/08/2017	Correspondence and approval documents
Get IRB approval for the clinical study	05/15/2017	05/15/2017	Correspondence and approval documents
Get feedback from at least 5 stroke-affected patients	05/05/2017	Mid-Late 2017	Force test results

# Dependencies

Dependency	Status	Resolve Plan and/or Actions Taken
Hardware from outside vendors (PCBs, printed/machined parts)	Resolved (Completed Date: 03/20/2017)	All parts needed for current design have already been acquired. Any fabrication that needs to be done can either be performed through a third party like ProtoLabs or in-house at a Hopkins-affiliated machine shop.
CES and IRB approval	'Unresolved' (Estimated Resolve Date: 05/05/2017)	If intractable delays in CES and IRB approval come up (unlikely since similar projects and devices from the same group have been approved in the past), the project will shift to focus more on technical development of the new prototype ( <u>which it has</u> ).
Patient recruiting	Unresolved (Estimated Resolve Date: 05/30/2017)	Even with CES and IRB approval, there can be delays in recruiting patients to participate in the study. If this occurs, many aspects of the design can be tested with healthy subjects, which are much easier to recruit.



# Revised Schedule



# References

---

- [1] AliExpress. (n.d.). [Image of Push Buttons, Snap Fasteners]. Retrieved March 25, 2017.
- [2] M&DC. (n.d.). [Image of Interrupted Screw Mechanism]. Retrieved March 25, 2017.
- [3] Olds, K. (n.d.). “System for Hand Rehabilitation” [Disclosure document]. Retrieved February 20, 2017.
- [4] PJRC. (n.d.). Teensy USB Development Board. Retrieved March 07, 2017, from <https://www.pjrc.com/teensy/index.html>.
- [5] Proto Labs. (n.d.). [Image of Logo]. Retrieved March 25, 2017.
- [5] BestValueVacs. (n.d.). [Image of Silicone Vacuum Pump]. Retrieved March 25, 2017.
- [6] Texas Instruments. (2011, January). “PGA309: Voltage Output Programmable Sensor Conditioner” [Data file and code book]. Retrieved March 07, 2017, from <http://www.ti.com/lit/ds/symlink/pga309.pdf>.
- [7] Texas Instruments. (2011, January). “PGA309: Voltage Output Programmable Sensor Conditioner User’s Guide” [Data file and code book]. Retrieved March 07, 2017, from <http://www.ti.com/lit/ug/sbou024b/sbou024b.pdf>.



# Q&A

---

Thank you for your time and attention!

